Paid Hardware Engineering Internship

End to End Product Development Summer Project
July – September 2021

The company is looking for a team of 3 passionate interns for a summer challenge project. The ideal candidates have a passion for product development and the drive to deliver results.

The Internship qualifies for the practical training required by UTCN.

About the Project

The project is a challenge to design and bring to life a new product variant within the timeframe of the internship. You will gain real-life experience of a product development process from research to prototype and you will be exposed to CAD Design, SBC Integration, Prototype Manufacturing Processes, Standalone Power Applications and much more.

What is Special about Us

1. We work with a broad variety of cool technologies:

- 6 Axis Robot
- Custom Industrial Screens
- PLC Control
- Linux and Android based SBC Custom Applications

2. We oversee full product design to manufacturing lifecycle:

- 3D CAD Design* (concept design, rendering)
- Product Development (prototyping, testing)
- Manufacturing (3D print, CNC, injection)
- Operations and Support (remote management, digital twin)
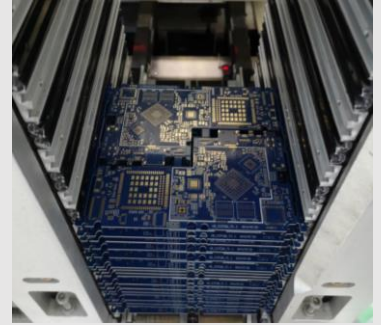 * Autodesk Suite (Inventor, Fusion 369, 3DS Max)

This is an example of a product that we have built end to end (GoodBox Core)

Candidates Requirements

- Analytical Mindset
- Perseverance
- Basic CAD Manipulation Skills
- Basic Electronics Knowledge (components and their functions)
- English: Basic Technical Writing and Conversational Fluency
- Basic C++ Coding Skills

How to Apply

Send an email to **hr@ngi.systems** containing:

- Subject Line "Hardware Engineering Internship"
- CV attached
- Answer to the below question

What is your top contribution to and end-to-end product delivery project?

Application Deadline: 15.06.2021

Career Launch Opportunity

We offer the option to extend the Internship to a paid 2 year **Accelerated Development Program** designed for flexibility that allows for the continuation of university studies alongside the program.

The ADP provides hands on experience that is complementing academic knowledge to develop a fully rounded hardware engineer.

The program creates the context to allow participants to make real contributions to live projects. Participants will benefit from coaching and mentoring, will develop 3D modelling and rendering skills, and learn how to manage projects.

Participants will have the opportunity to travel to factories in China and site locations in the UK.